

### GENERAL DESCRIPTION



The ICS87946I is a low skew, ÷1, ÷2 LVCMOS Clock Generator and a member of the HiPerClockS™ family of High Performance Clock Solutions from ICS. The ICS87946I has two selectable single ended clock inputs. The single ended

clock inputs accept LVCMOS or LVTTL input levels. The low impedance LVCMOS outputs are designed to drive  $50\Omega$  series or parallel terminated transmission lines. The effective fanout can be increased from 10 to 20 by utilizing the ability of the outputs to drive two series terminated lines.

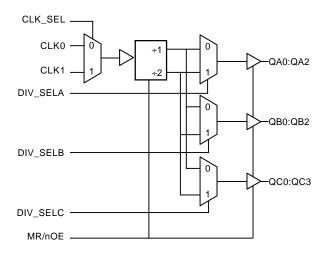
The divide select inputs, DIV\_SELx, control the output frequency of each bank. The outputs can be utilized in the  $\div 1$ ,  $\div 2$  or a combination of  $\div 1$  and  $\div 2$  modes. The master reset input, MR/nOE, resets the internal frequency dividers and also controls the active and high impedance states of all outputs.

The ICS87946I is characterized at 3.3V core/3.3V output. Guaranteed output and part-to-part skew characteristics make the ICS87946I ideal for those clock distribution applications demanding well defined performance and repeatability.

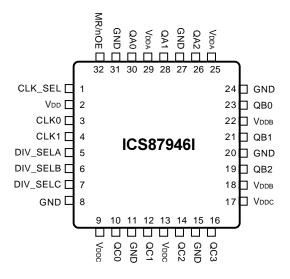
### **F**EATURES

- 10 single ended LVCMOS outputs, 7Ω typical output impedance
- Selectable CLK0 and CLK1 LVCMOS clock inputs
- CLK0 and CLK1 can accept the following input levels: LVCMOS and LVTTL
- · Output skew: 350ps (maximum)
- 3.3V input, 3.3V outputs
- -40°C to 85°C ambient operating temperature
- Pin compatible to the MPC946

## **BLOCK DIAGRAM**



## PIN ASSIGNMENT



32-Lead LQFP 7mm x 7mm x 1.4mm Y Package Top View



### TABLE 1. PIN DESCRIPTIONS

Number	Name	Ty	/ре	Description
1	CLK_SEL	Input	Pulldown	Clock select input. When HIGH, selects CLK1. When LOW, selects CLK0. LVCMOS / LVTTL interface levels.
2	$V_{_{\mathrm{DD}}}$	Power		Positive supply pins.
3, 4	CLK0, CLK1	Input	Pullup	LVCMOS / LVTTL clock inputs.
5	DIV_SELA	Input	Pulldown	Controls frequency division for Bank A outputs.  LVCMOS / LVTTL interface levels.
6	DIV_SELB	Input	Pulldown	Controls frequency division for Bank B outputs.  LVCMOS / LVTTL interface levels.
7	DIV_SELC	Input	Pulldown	Controls frequency division for Bank C outputs.  LVCMOS / LVTTL interface levels.
8, 11, 15, 20, 24, 27, 31	GND	Power		Power supply ground.
9, 13, 17	$V_{\scriptscriptstyle DDC}$	Power		Positive supply pins for Bank C outputs.
10, 12, 14, 16	QC0, QC1, QC2, QC3	Output		Bank C outputs. LVCMOS / LVTTL interface levels. $7\Omega$ typical output impedance.
18, 22	$V_{\scriptscriptstyle DDB}$	Power		Positive supply pins for Bank B outputs.
19, 21, 23	QB2, QB1, QB0	Output		Bank B outputs. LVCMOS / LVTTL interface levels. 7Ω typical output impedance.
25, 29	$V_{\scriptscriptstyle DDA}$	Power		Positive supply pins for Bank A outputs.
26, 28, 30	QA2, QA1, QA0	Output		Bank A outputs. LVCMOS / LVTTL interface levels. 7Ω typical output impedance.
32	MR/nOE	Input	Pulldown	Master reset and output enable. Resets outputs to tristate. Enables and disables all outputs. LVCMOS / LVTTL interface levels.

NOTE: Pullup and Pulldown refer to internal input resistors. See Table 2, Pin Characteristics, for typical values.

TABLE 2. PIN CHARACTERISTICS

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C <sub>IN</sub>	Input Capacitance				4	pF
R <sub>PULLUP</sub>	Input Pullup Resistor			51		ΚΩ
R <sub>PULLDOWN</sub>	Input Pulldown Resistor			51		ΚΩ
C <sub>PD</sub>	Power Dissipation Capacitance (per output); NOTE 1	$V_{DD}$ , $V_{DDx} = 3.6V$		25		pF
R <sub>out</sub>	Output Impedance			7		Ω

NOTE 1:  $V_{\rm DDx}$  denotes  $V_{\rm DDA}$ ,  $V_{\rm DDB}$ ,  $V_{\rm DDC}$ .

TABLE 3. FUNCTION TABLE

Inputs				Outputs			
MR/nOE	DIV_SELA	DIV_SELB	DIV_SELC	QA0:QA2	QB0:QB2	QC0:QC3	
1	X	Х	X	Hi Z	Hi Z	Hi Z	
0	0	X	X	fIN/1	Active	Active	
0	1	X	Х	fIN/2	Active	Active	
0	Х	0	Х	Active	fIN/1	Active	
0	X	1	Х	Active	fIN/2	Active	
0	Х	Х	0	Active	Active	fIN/1	
0	Х	Х	1	Active	Active	fIN/2	



#### ABSOLUTE MAXIMUM RATINGS

Supply Voltage,  $V_{DDx}$  4.6V

 $\begin{array}{ll} \text{Inputs, V}_{\text{I}} & -0.5\text{V to V}_{\text{DD}} + 0.5\text{V} \\ \text{Outputs, V}_{\text{O}} & -0.5\text{V to V}_{\text{DDx}} + 0.5\text{V} \\ \text{Package Thermal Impedance, } \theta_{\text{JA}} & 47.9^{\circ}\text{C/W (0 lfpm)} \\ \text{Storage Temperature, T}_{\text{STG}} & -65^{\circ}\text{C to } 150^{\circ}\text{C} \\ \end{array}$ 

Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

Table 4A. Power Supply DC Characteristics,  $V_{DD} = V_{DDx} = 3.3V \pm 0.3V$ , Ta = -40°C to 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{DD}$	Positive Supply Voltage		3.0	3.3	3.6	V
V <sub>DDx</sub>	Output Supply Voltage; NOTE 1		3.0	3.3	3.6	V
I <sub>DD</sub>	Power Supply Current				85	mA

NOTE 1: V<sub>DDx</sub> denotes V<sub>DDA</sub>, V<sub>DDB</sub>, V<sub>DDC</sub>.

Table 4B. LVCMOS DC Characteristics,  $V_{DD} = V_{DDx} = 3.3V \pm 0.3V$ , Ta = -40°C to 85°C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
V <sub>IH</sub>	Input High Voltage	DIV_SELA, DIV_SELB, DIV_SELC, CLK_SEL, MR/nOE		2		V <sub>DD</sub> + 0.3	V
		CLK0, CLK1		2		$V_{DD} + 0.3$	V
V <sub>IL</sub>	Input Low Voltage	DIV_SELA, DIV_SELB, DIV_SELC, CLK_SEL, MR/nOE		-0.3		0.8	V
		CLK0, CLK1		-0.3		1.3	V
I <sub>IH</sub>	Input High Current	DIV_SELA, DIV_SELB, DIV_SELC, CLK_SEL, MR/nOE	$V_{DD} = V_{IN} = 3.6V$			120	μΑ
		CLK0, CLK1	$V_{DD} = V_{IN} = 3.6V$			5	μΑ
I <sub>IL</sub>	Input Low Current	DIV_SELA, DIV_SELB, DIV_SELC, CLK_SEL, MR/nOE	$V_{DD} = 3.6V, V_{IN} = 0V$	-5			μΑ
		CLK0, CLK1	$V_{DD} = 3.6V, V_{IN} = 0V$	-120			μA
V <sub>OH</sub>	Output High Voltage		I <sub>OH</sub> = -20mA	2.5			V
V <sub>OL</sub>	Output Low Voltage		I <sub>OL</sub> = 20mA			0.4	V

## Integrated Circuit Systems, Inc.

Table 5. AC Characteristics,  $V_{DD} = V_{DDx} = 3.3V \pm 0.3V$ , Ta = -40°C to 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
f <sub>MAX</sub>	Input Frequency		150			MHz
tp <sub>LH</sub>	Propagation Delay, Low to High; NOTE 1		2	4	6	ns
tp <sub>HL</sub>	Propagation Delay, High to Low; NOTE 1		2	4	6	ns
tsk(o)	Output Skew; NOTE 2, 6				350	ps
4-1-()	Multiple Frequency Skew;	f <sub>MAX</sub> < 100MHz			350	ps
tsk(w)	NOTE 3, 6	$f_{MAX} > 100MHz$			450	ps
tsk(pp)	Part-to-Part Skew; NOTE 4, 6				4.5	ns
t <sub>R</sub>	Output Rise Time; NOTE 5	0.8V to 2.0V	0.1		1.0	ns
t <sub>F</sub>	Output Fall Time; NOTE 5	0.8V to 2.0V	0.1		1.0	ns
t <sub>EN</sub>	Output Enable Time; NOTE 5				11	ns
t <sub>DIS</sub>	Output Disable Time; NOTE 5				11	ns

NOTE 1: Measured from the  $V_{DD}/2$  of the input to  $V_{DDx}/2$  of the output. NOTE 2: Defined as skew across banks of outputs at the same supply voltages and with equal load conditions.

Measured at V<sub>DDx</sub>/2.

NOTE 3: Defined as skew across banks of outputs operating at different frequencies with the same supply voltages and equal load conditions.

NOTE 4: Defined as skew between outputs on different devices operating at the same supply voltages and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at V<sub>DDx</sub>/2.

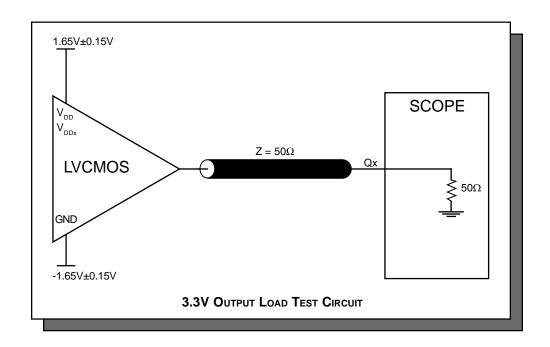
NOTE 5: These parameters are guaranteed by characterization. Not tested in production.

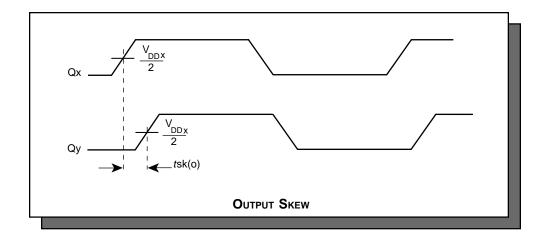
NOTE 6: This parameter is defined in accordance with JEDEC Standard 65.

NOTE:  $V_{DDx}$  denotes  $V_{DDA}$ ,  $V_{DDB}$ ,  $V_{DDC}$ .

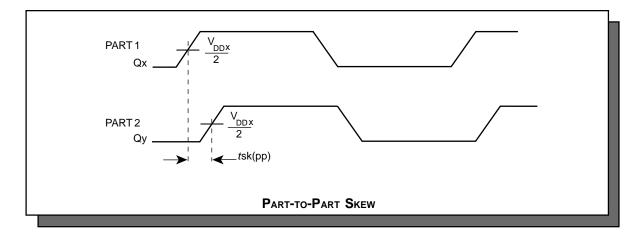


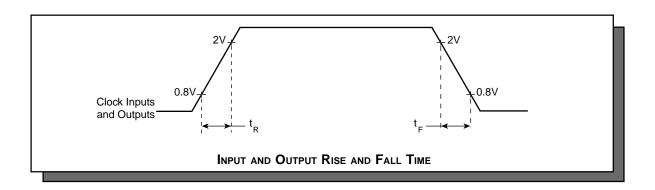
# PARAMETER MEASUREMENT INFORMATION

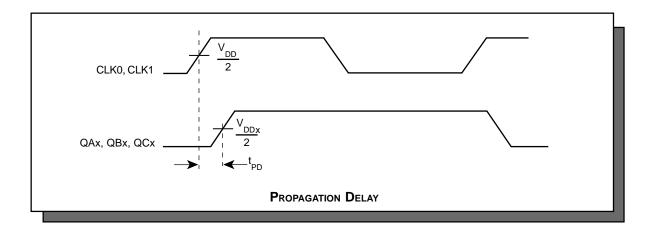














# RELIABILITY INFORMATION

## Table 6. $\theta_{\rm JA} \text{vs. A} \text{ir Flow Table}$

## $\theta_{\text{JA}}$ by Velocity (Linear Feet per Minute)

	0	200	500
Single-Layer PCB, JEDEC Standard Test Boards	67.8°C/W	55.9°C/W	50.1°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	47.9°C/W	42.1°C/W	39.4°C/W

NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

### TRANSISTOR COUNT

The transistor count for ICS87946I is: 1204



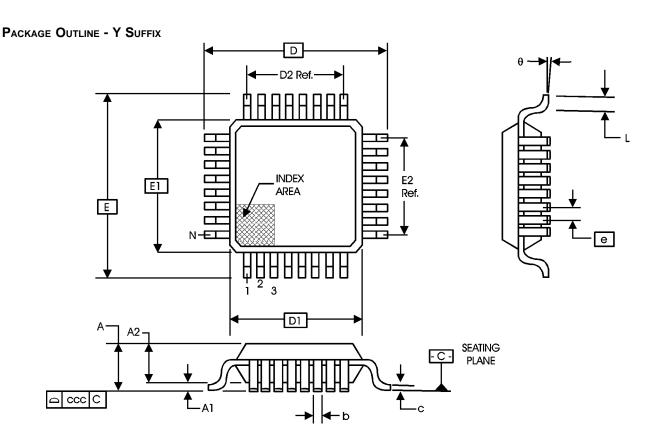


TABLE 7. PACKAGE DIMENSIONS

JEDEC VARIATION ALL DIMENSIONS IN MILLIMETERS							
OVIII O	ВВА						
SYMBOL	MINIMUM	NOMINAL	MAXIMUM				
N		32					
Α			1.60				
<b>A</b> 1	0.05		0.15				
A2	1.35	1.40	1.45				
b	0.30	0.37	0.45				
c	0.09	0.09 0.20					
D		9.00 BASIC					
D1		7.00 BASIC					
D2		5.60 Ref.					
E		9.00 BASIC					
E1		7.00 BASIC					
E2		5.60 Ref.					
е		0.80 BASIC					
L	0.45	0.60	0.75				
θ	0°		7°				
ccc			0.10				

Reference Document: JEDEC Publication 95, MS-026



# **ICS87946I**

LOW SKEW, ÷1, ÷2 LVCMOS CLOCK GENERATOR

#### TABLE 8. ORDERING INFORMATION

Part/Order Number	Marking	Package	Count	Temperature
ICS87946AYI	ICS87946AYI	32 Lead LQFP	250 per tray	-40°C to 85°C
ICS87946AYIT	ICS87946AYI	32 Lead LQFP on Tape and Reel	1000	-40°C to 85°C

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